

SEMICONDUCTOR STRUCTURE AND METHOD FOR MANUFACTURING SEMICONDUCTOR STRUCTURE, MEMORY CHIP AND ELECTRONIC DEVICE

ABSTRACT

The embodiments of the disclosure relate to the field of semiconductors and provide a semiconductor structure and a method for manufacturing the semiconductor structure, a memory chip and an electronic device. The semiconductor structure comprises a substrate on which a stacked structure is provided, the stacked structure comprising a plurality of memory cell groups arranged in a first direction, each of the memory cell groups comprising multiple layers of memory cells arranged in a second direction; and a plurality of leading wire posts, wherein at least two leading wire posts are respectively in contact with the memory cells of different layers in different memory cell groups. The embodiments of the disclosure can at least improve an integration level of the semiconductor structure.

[Fig. 4]